AM26C32 四路差动线路接收器

1 特性

- 符合或超出了 ANSI TIA/EIA-422-B、TIA/EIA-423-B 和 ITU 建议 V.10 与 V.11 的要求。
- 低功耗，I_{CC} = 10mA（典型值）
- 具有 ±200mV 灵敏度的 ±7V 共模范围
- 输入迟滞：60mV（典型值）
- t_{pd} = 17ns（典型值）
- 采用 5V 单电源供电
- 三态输出
- 输入失效防护电路
- 是 AM26LS32 器件的改良替代品
- 可用于 Q-Temp 汽车

2 应用

- 高可靠性汽车 应用
- 工厂自动化
- ATM 和点钞机
- 智能电网
- 交流和伺服电机驱动器

3 说明

AM26C32 器件是一款四路差动线路接收器，用于平衡或不平衡的数字数据传输。四个接收器均具有使能功能，该功能提供了两种可选输入：高电平有效输入和低电平有效输入。通过三态输出，该器件可直接连接至总线组织式系统。失效防护设计规定当输入处于开路状态时，输出始终为高电平。

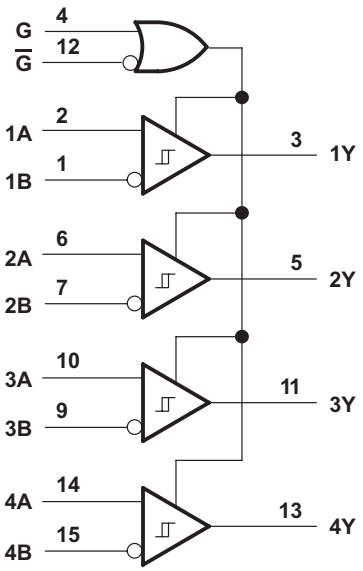
AM26C32 器件采用 BiCMOS 工艺制造，该工艺有效集成了双极晶体管和 CMOS 晶体管。通过该工艺，即可实现双极晶体管的耐高电压大电流特性又可实现 CMOS 的低功耗特性，器件功耗降低至 AM26LS32 标准器件的五分之一左右，同时仍可保持交流和直流性能。

器件信息(1)

器件编号	封装	封装尺寸（标称值）
AM26C32N	PDIP (16)	19.30mm x 6.35mm
AM26C32NS	SO (16)	10.20mm × 5.30mm
AM26C32D	SOIC (16)	9.90mm × 3.90mm
AM26C32PW	TSSOP (16)	5.00mm × 4.40mm
AM26C32J	陶瓷双列直插封装 (CDIP) (16)	21.34mm × 6.92mm
AM26C32W	CFP (16)	10.16mm × 6.73mm
AM26C32FK	LCCC (20)	8.90mm × 8.90mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

简化原理图



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4 修订历史记录

Changes from Revision K (June 2015) to Revision L **Page**

- Changed I_I unit value From: µA To: mA in the *Electrical Characteristics* table ... 5

Changes from Revision J (February 2014) to Revision K **Page**

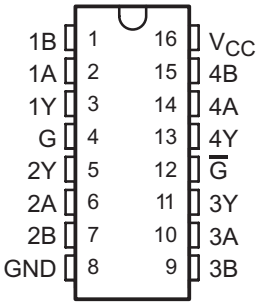
- 添加了*引脚配置和功能* 部分、*ESD 额定值* 表、*特性 说明*部分、*器件功能模式*、*应用和实施*部分、*电源建议*部分、*布局*部分、*器件和文档支持*部分以及*机械、封装和可订购信息*部分 ... 1

Changes from Revision I (September 2004) to Revision J **Page**

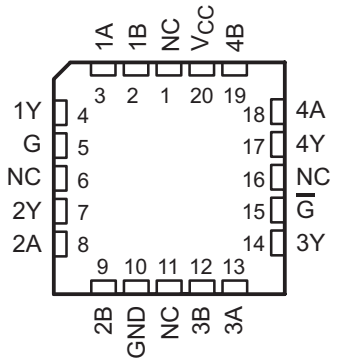
- 将文档更新为新的 TI 产品说明书格式 - 无规格变化 ... 1
- 删除了*订购信息*表。 ... 1
- 已更新*特性* ... 1
- Added ESD Warning ... 3

5 Pin Configuration and Functions

D, N, NS, PW, J or W Package
16-Pin SOIC, PDIP, SO, TSSOP, CDIP, or CFP
Top View



FK Package
20-Pin LCCC
Top View



Pin Functions

PIN			I/O	DESCRIPTION
NAME	LCCC	SOIC, PDIP, SO, TSSOP, CFP, or CDIP		
1A	3	2	I	RS422/RS485 differential input (noninverting)
1B	2	1	I	RS422/RS485 differential input (inverting)
1Y	4	3	O	Logic level output
2A	8	6	I	RS422/RS485 differential input (noninverting)
2B	9	7	I	RS422/RS485 differential input (inverting)
2Y	7	5	O	Logic level output
3A	13	10	I	RS422/RS485 differential input (noninverting)
3B	12	9	I	RS422/RS485 differential input (inverting)
3Y	14	11	O	Logic level output
4A	18	14	I	RS422/RS485 differential input (noninverting)
4B	19	15	I	RS422/RS485 differential input (inverting)
4Y	17	13	O	Logic level output
G	5	4	I	Active-high select
$\overline{G}$	15	12	I	Active-low select
GND	10	8	—	Ground
NC(1)	1	—	—	Do not connect
	6			
	11			
	16			
V_{CC}	20	16	—	Power Supply

(1) NC – no internal connection.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage (2)			7	V
V_I	Input voltage	A or B inputs	–11	14	V
		G or $\overline{G}$ inputs	–0.5	V_{CC} + 0.5	
V_{ID}	Differential input voltage		–14	14	V
V_O	Output voltage		–0.5	V_{CC} + 0.5	V
I_O	Output current			±25	mA
T_{stg}	Storage temperature		-65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential voltages, are with respect to the network ground terminal.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±3000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±2000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage		2		V_{cc}	V
V_{IL}	Low-level input voltage		0		0.8	V
V_{IC}	Common-mode input voltage		-7		+7	V
I_{OH}	High-level output current				–6	mA
I_{OL}	Low-level output current				6	mA
T_A	Operating free-air temperature	AM26C32C	0		70	°C
		AM26C32I	–40		85	
		AM26C32Q	–40		125	
		AM26C32M	–55		125	

6.4 Thermal Information

THERMAL METRIC (1)		AM26C32				UNIT
		D (SOIC)	N (PDIP)	NS (SO)	PW (TSSOP)	
		16 PINS	16 PINS	16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	73	67	64	108	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
V_{IT+}	Differential input high-threshold voltage	$V_O = V_{OH(min)}$, I_{OH} = –440 µA	V_{IC} = –7 V to 7 V			0.2	V
			V_{IC} = 0 V to 5.5 V			0.1	
V_{IT-}	Differential input low-threshold voltage	V_O = 0.45 V, I_{OL} = 8 mA	V_{IC} = –7 V to 7 V	–0.2(2)			V
			V_{IC} = 0 V to 5.5 V	–0.1(2)			
V_{hys}	Hysteresis voltage ($V_{IT+} – V_{IT-}$)				60		mV
V_{IK}	Enable input clamp voltage	V_{CC} = 4.5 V, I_I = –18 mA				–1.5	V
V_{OH}	High-level output voltage	V_{ID} = 200 mV, I_{OH} = –6 mA		3.8			V
V_{OL}	Low-level output voltage	V_{ID} = –200 mV, I_{OL} = 6 mA			0.2	0.3	V
I_{OZ}	OFF-state (high-impedance state) output current	$V_O = V_{CC}$ or GND			±0.5	±5	µA
I_I	Line input current	V_I = 10 V, Other input at 0 V				1.5	mA
		V_I = –10 V, Other input at 0 V				–2.5	mA
I_{IH}	High-level enable current	V_I = 2.7 V				20	µA
I_{IL}	Low-level enable current	V_I = 0.4 V				–100	µA
r_i	Input resistance	One input to ground		12	17		kΩ
I_{CC}	Quiescent supply current	V_{CC} = 5.5 V			10	15	mA

(1) All typical values are at V_{CC} = 5 V, V_{IC} = 0, and T_A = 25°C.
(2) The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage.

6.6 Switching Characteristics

over operating free-air temperature range, C_L = 50 pF (unless otherwise noted)

PARAMETER		TEST CONDITIONS	AM26C32C AM26C32I			AM26C32Q AM26C32M			UNIT
			MIN	TYP(1)	MAX	MIN	TYP(1)	MAX	
t_{PLH}	Propagation delay time, low- to high-level output	See Figure 2	9	17	27	9	17	27	ns
t_{PHL}	Propagation delay time, high- to low-level output		9	17	27	9	17	27	ns
t_{TLH}	Output transition time, low- to high-level output	See Figure 2		4	9		4	10	ns
t_{THL}	Output transition time, high- to low-level output			4	9		4	9	ns
t_{PZH}	Output enable time to high-level	See Figure 3		13	22		13	22	ns
t_{PZL}	Output enable time to low-level			13	22		13	22	ns
t_{PHZ}	Output disable time from high-level	See Figure 3		13	22		13	26	ns
t_{PLZ}	Output disable time from low-level			13	22		13	25	ns

(1) All typical values are at V_{CC} = 5 V, T_A = 25°C.

6.7 Typical Characteristics

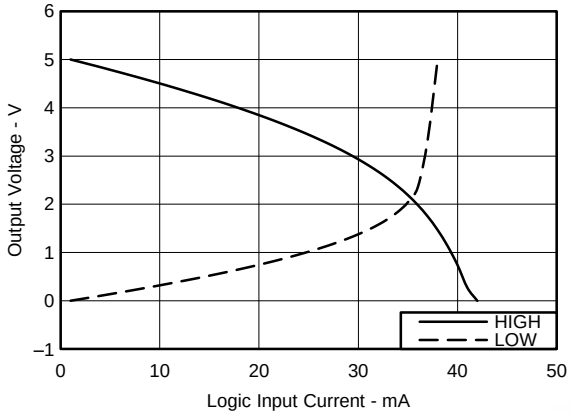
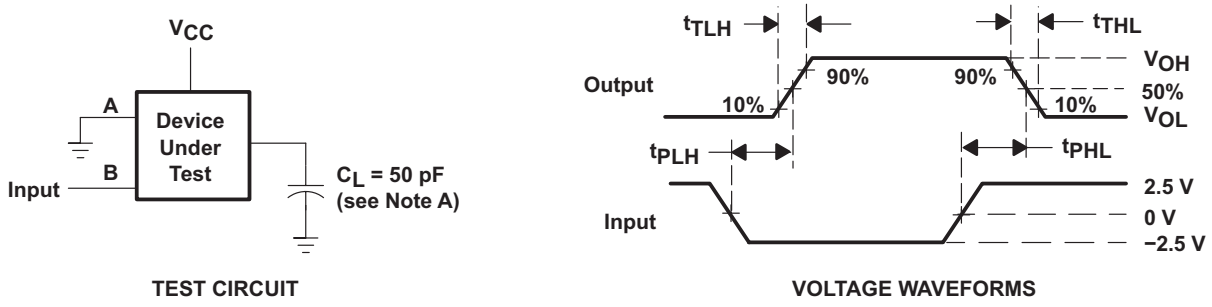


Figure 1. Output Voltage vs Input Current

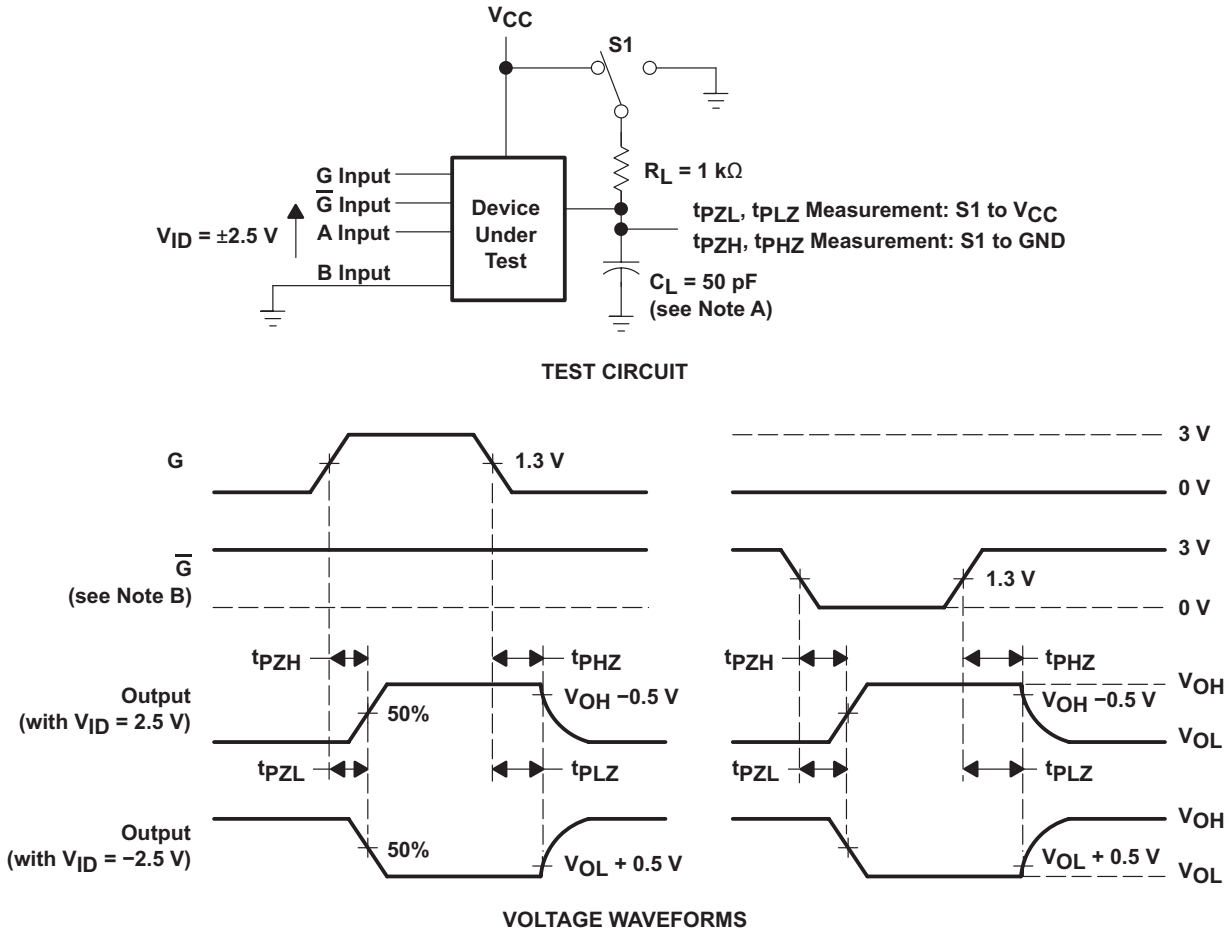
7 Parameter Measurement Information



TEST CIRCUIT VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

Figure 2. Switching Test Circuit and Voltage Waveforms



A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle ≤ 50%, $t_r = t_f$ = 6 ns.

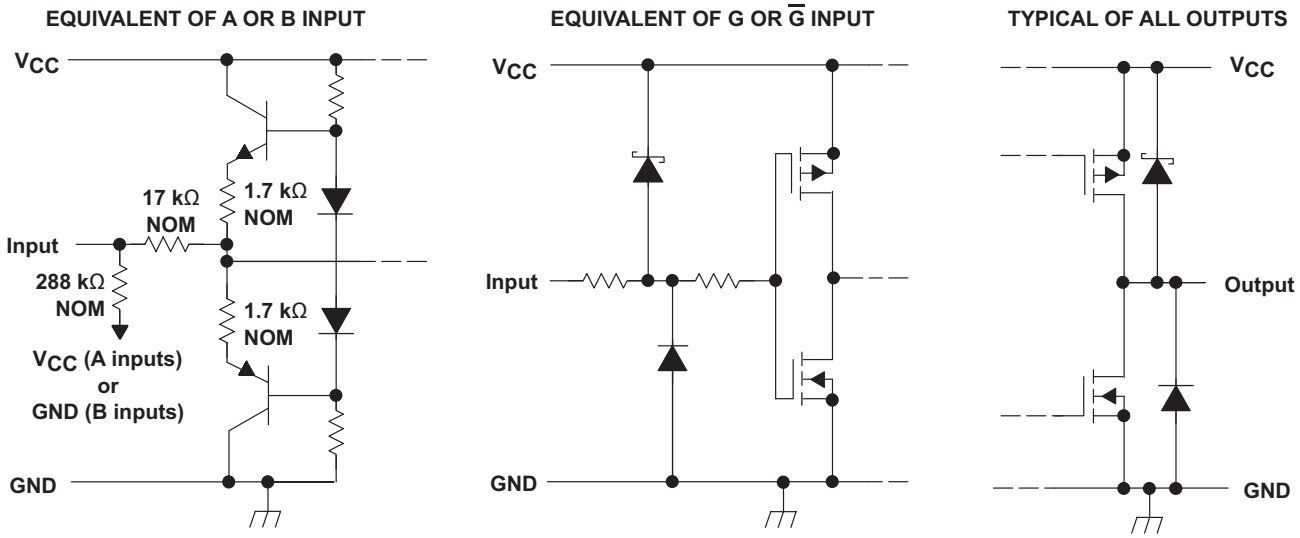
Figure 3. Enable/Disable Time Test Circuit and Output Voltage Waveforms

8 Detailed Description

8.1 Overview

The AM26C32 is a quadruple differential line receiver that meets the necessary requirements for NSI TIA/EIA-422-B, TIA/EIA-423-B, and ITU Recommendation V.10 and V.11. This device allows a low power or low voltage MCU to interface with heavy machinery, subsystems and other devices through long wires of up to 1000m, giving any design a reliable and easy to use connection. As any RS422 interface, the AM26C32 works in a differential voltage range, which enables very good signal integrity.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 ±7-V Common-Mode Range With ±200-mV Sensitivity

For a common-mode voltage varying from -7V to 7V, the input voltage is acceptable in low ranges greater than 200 mV as a standard.

8.3.2 Input Fail-Safe Circuitry

RS-485 specifies that the receiver output state should be logic high for differential input voltages of $V_{AB} \geq +200$ mV and logic low for $V_{AB} \leq -200$ mV. For input voltages in between these limits, a receiver's output state is not defined and can randomly assume high or low. Removing the uncertainty of random output states, modern transceiver designs include internal biasing circuits that put the receiver output into a defined state (typically high) in the absence of a valid input signal.

A loss of input signal can be caused by an pen circuit caused by a wire break or the unintentional disconnection of a transceiver from the bus. The AM26C32 has an internal circuit that ensures functionality during an idle bus.

8.3.3 Active-High and Active-Low

The device can be configure using the G and $\overline{G}$ logic inputs to select receiver output. The high voltage or logic 1 on the G pin, allows the device to operate on an active-high and having a low voltage or logic 0 on the $\overline{G}$ enables active low operation. These are simply a way to configure the logic to match that of the receiving or transmitting controller or microprocessor.

8.3.4 Operates from a Single 5-V Supply

Both the logic and receivers operate from a single 5-V rail, making designs much more simple. The line drivers and receivers can operate off the same rail as the host controller or a similar low voltage supply, thus simplifying power structure.

8.4 Device Functional Modes

8.4.1 Enable and Disable

The receivers implemented in these RS422 devices can be configured using the G and $\overline{G}$ pins to be enabled or disabled. This allows users to ignore or filter out transmissions as desired.

Table 1. Function Table (Each Receiver)

DIFFERENTIAL INPUT	ENABLES		OUTPUT
A/B	G	$\overline{G}$	Y
$V_{ID} \geq V_{IT+}$	H	X	H
	X	L	H
$V_{IT} < V_{ID} < V_{IT+}$	H	X	?
	X	L	?
$V_{ID} \leq V_{IT-}$	H	X	L
	X	L	L
X	L	H	Z

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

When designing a system that uses drivers, receivers, and transceivers that comply with RS-422 or RS-485, proper cable termination is essential for highly reliable applications with reduced reflections in the transmission line. Because RS-422 allows only one driver on the bus, if termination is used, it is placed only at the end of the cable near the last receiver. In general, RS-485 requires termination at both ends of the cable. Factors to consider when determining the type of termination usually are performance requirements of the application and the ever-present factor, cost. The different types of termination techniques discussed are unterminated lines, parallel termination, AC termination, and multipoint termination. Laboratory waveforms for each termination technique (except multipoint termination) illustrate the usefulness and robustness of RS-422 (and, indirectly, RS-485). Similar results can be obtained if 485-compliant devices and termination techniques are used. For laboratory experiments, 100 feet of 100-Ω, 24-AWG, twisted-pair cable (Bertek) was used. A single driver and receiver, TI AM26C31C and AM26C32C, respectively, were tested at room temperature with a 5-V supply voltage. Two plots per termination technique are shown. In each plot, the top waveform is the driver input and the bottom waveform is the receiver output. To show voltage waveforms related to transmission-line reflections, the first plot shows output waveforms from the driver at the start of the cable; the second plot shows input waveforms to the receiver at the far end of the cable.

9.2 Typical Application

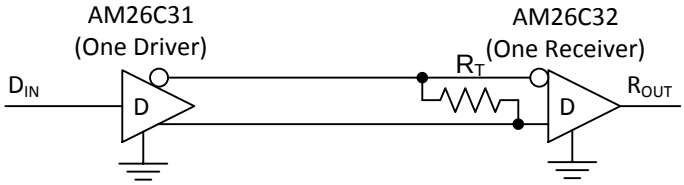


Figure 4. Differential Terminated Configuration

9.2.1 Design Requirements

Resistor and capacitor (if used) termination values are shown for each laboratory experiment, but vary from system to system. For example, the termination resistor, R_T, must be within 20% of the characteristic impedance, Zo , of the cable and can vary from about 80 Ω to 120 Ω.

9.2.2 Detailed Design Procedure

Figure 4 shows a configuration with no termination. Although reflections are present at the receiver inputs at a data signaling rate of 200 kbps with no termination, the RS-422-compliant receiver reads only the input differential voltage and produces a clean signal at the output.

Typical Application (continued)

9.2.3 Application Curve

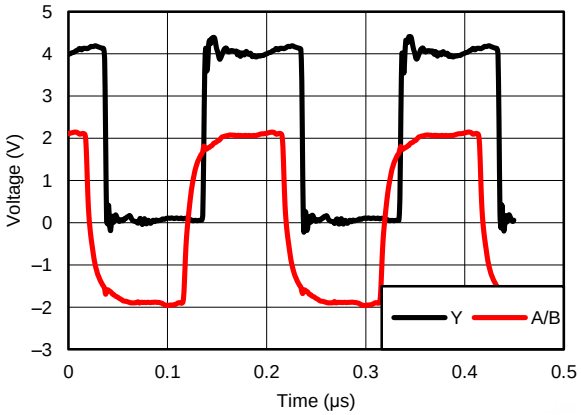


Figure 5. Differential 120-Ω Terminated Output Waveforms (Cat 5E Cable)

10 Power Supply Recommendations

Place 0.1-μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high impedance power supplies.

11 Layout

11.1 Layout Guidelines

For best operational performance of the device, use good PCB layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole, as well as the operational amplifier. Bypass capacitors are used to reduce the coupled noise by providing low impedance power sources local to the analog circuitry.
  - Connect low-ESR, 0.1-μF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- To reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If it is not possible to keep them separate, it is much better to cross the sensitive trace perpendicular as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. Keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.

11.2 Layout Example

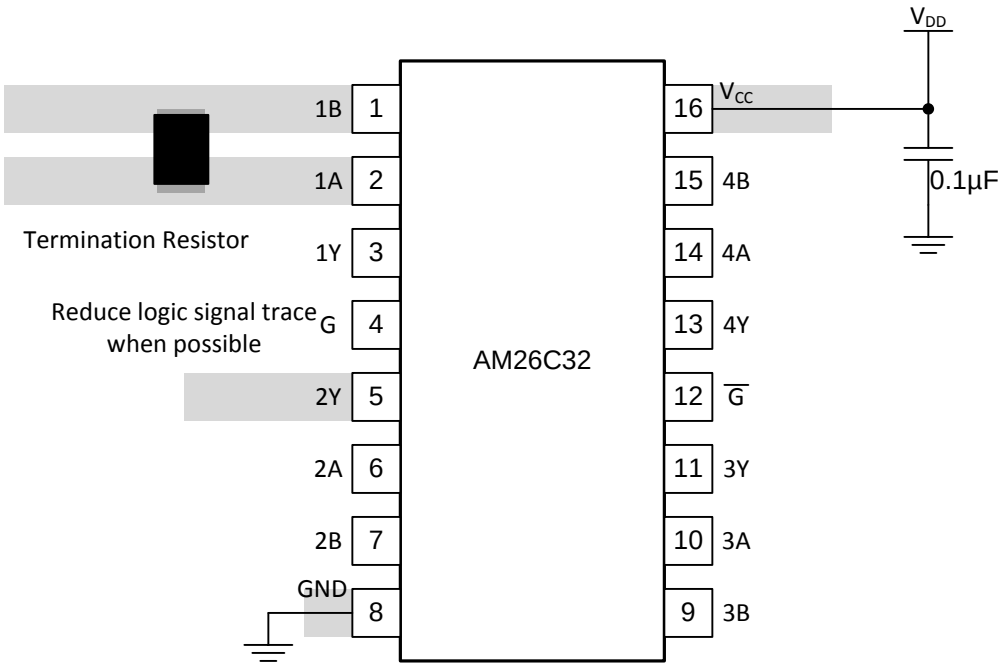


Figure 6. Trace Layout on PCB and Recommendations

12 器件和文档支持

12.1 接收文档更新通知

要接收文档更新通知，请导航至 TI.com.cn 上的器件产品文件夹。单击右上角的*通知我* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

12.2 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商“按照原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 《使用条款》。

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12.3 商标

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All other trademarks are the property of their respective owners.

12.4 静电放电警告

这些装置包含有限的内置 ESD 保护。 存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

12.5 术语表

SLYZ022 — *TI 术语表*。

这份术语表列出并解释术语、缩写和定义。

13 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9164001Q2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9164001Q2A AM26C32 MFKB	Samples
5962-9164001QEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9164001QEA AM26C32MJB	Samples
5962-9164001QFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9164001QFA AM26C32MWB	Samples
AM26C32CD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AM26C32C	Samples
AM26C32CDBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		26C32	Samples
AM26C32CDE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AM26C32C	Samples
AM26C32CDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AM26C32C	Samples
AM26C32CDRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AM26C32C	Samples
AM26C32CN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	AM26C32CN	Samples
AM26C32CNE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	AM26C32CN	Samples
AM26C32CNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	26C32	Samples
AM26C32ID	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM26C32I	Samples
AM26C32IDE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM26C32I	Samples
AM26C32IDG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM26C32I	Samples
AM26C32IDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM26C32I	Samples
AM26C32IDRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM26C32I	Samples
AM26C32IDRG4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM26C32I	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
AM26C32IN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	AM26C32IN	Samples
AM26C32INSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26C32I	Samples
AM26C32IPW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26C32I	Samples
AM26C32IPWG4	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26C32I	Samples
AM26C32IPWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26C32I	Samples
AM26C32IPWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26C32I	Samples
AM26C32MFKB	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9164001Q2A AM26C32 MFKB	Samples
AM26C32MJB	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9164001QE A AM26C32MJB	Samples
AM26C32MWB	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9164001QF A AM26C32MWB	Samples
AM26C32QD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AM26C32Q	Samples
AM26C32QDG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	26C32Q	Samples
AM26C32QDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AM26C32Q	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF AM26C32, AM26C32M :

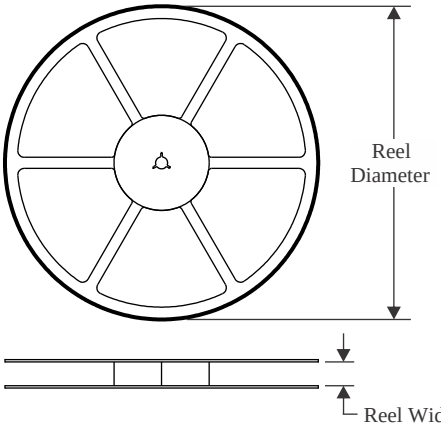
- Catalog : AM26C32
- Enhanced Product : AM26C32-EP, AM26C32-EP
- Military : AM26C32M

NOTE: Qualified Version Definitions:

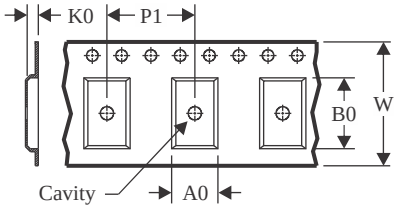
- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

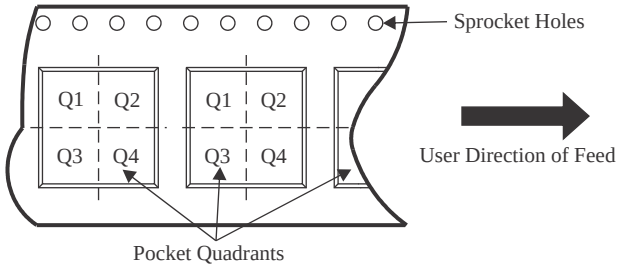


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

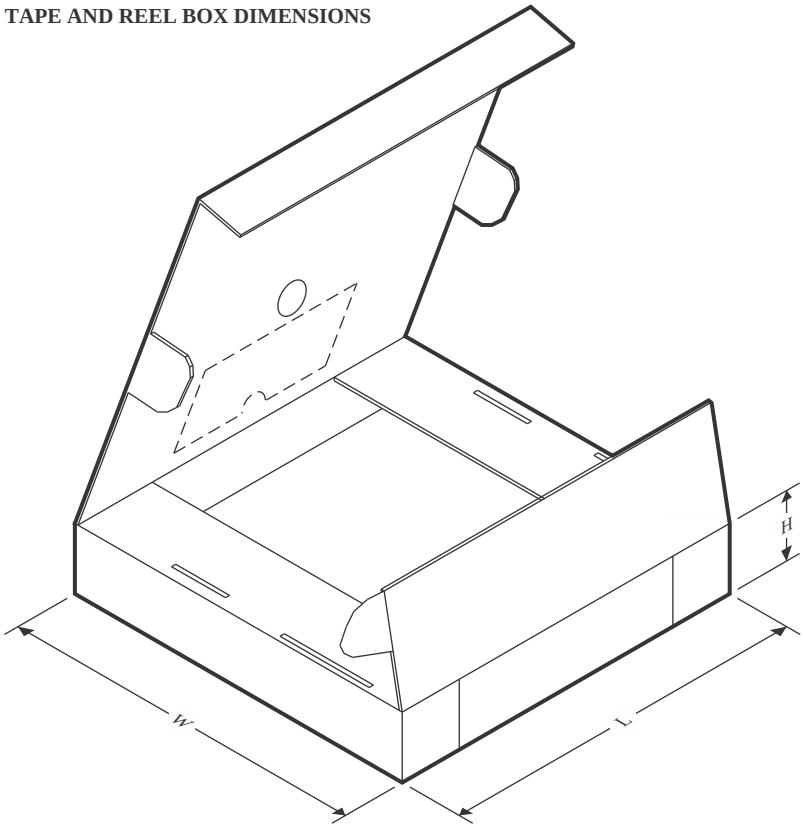
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AM26C32CDBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
AM26C32CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26C32CNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
AM26C32IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26C32INSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
AM26C32IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
AM26C32QDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

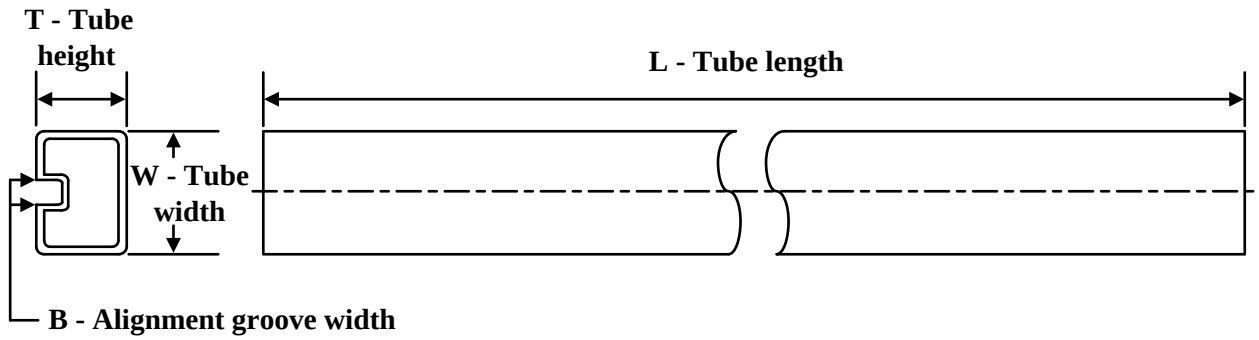
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AM26C32CDBR	SSOP	DB	16	2000	356.0	356.0	35.0
AM26C32CDR	SOIC	D	16	2500	340.5	336.1	32.0
AM26C32CNSR	SO	NS	16	2000	356.0	356.0	35.0
AM26C32IDR	SOIC	D	16	2500	340.5	336.1	32.0
AM26C32INSR	SO	NS	16	2000	367.0	367.0	38.0
AM26C32IPWR	TSSOP	PW	16	2000	367.0	367.0	35.0
AM26C32QDR	SOIC	D	16	2500	350.0	350.0	43.0

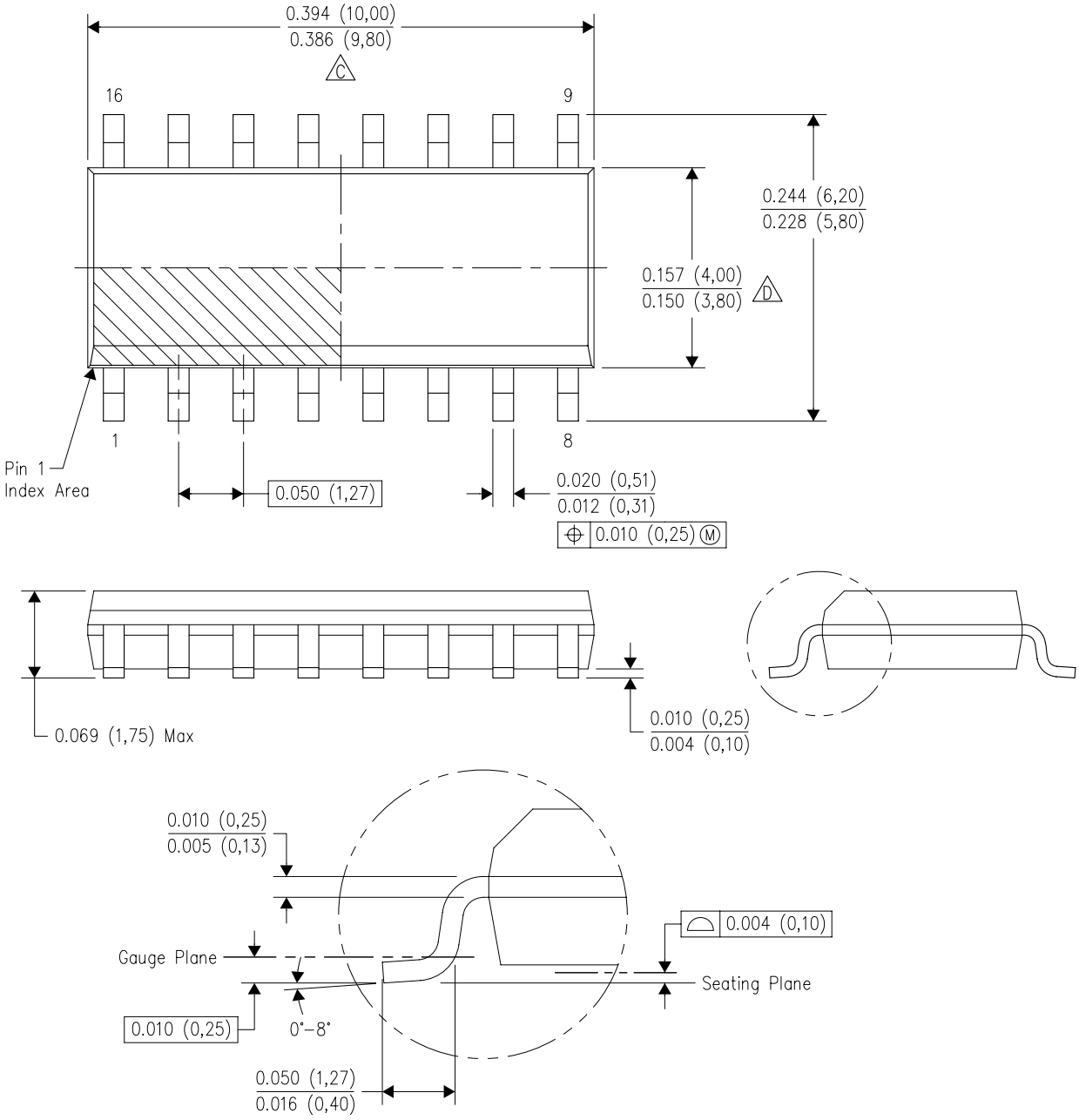
TUBE



*All dimensions are nominal

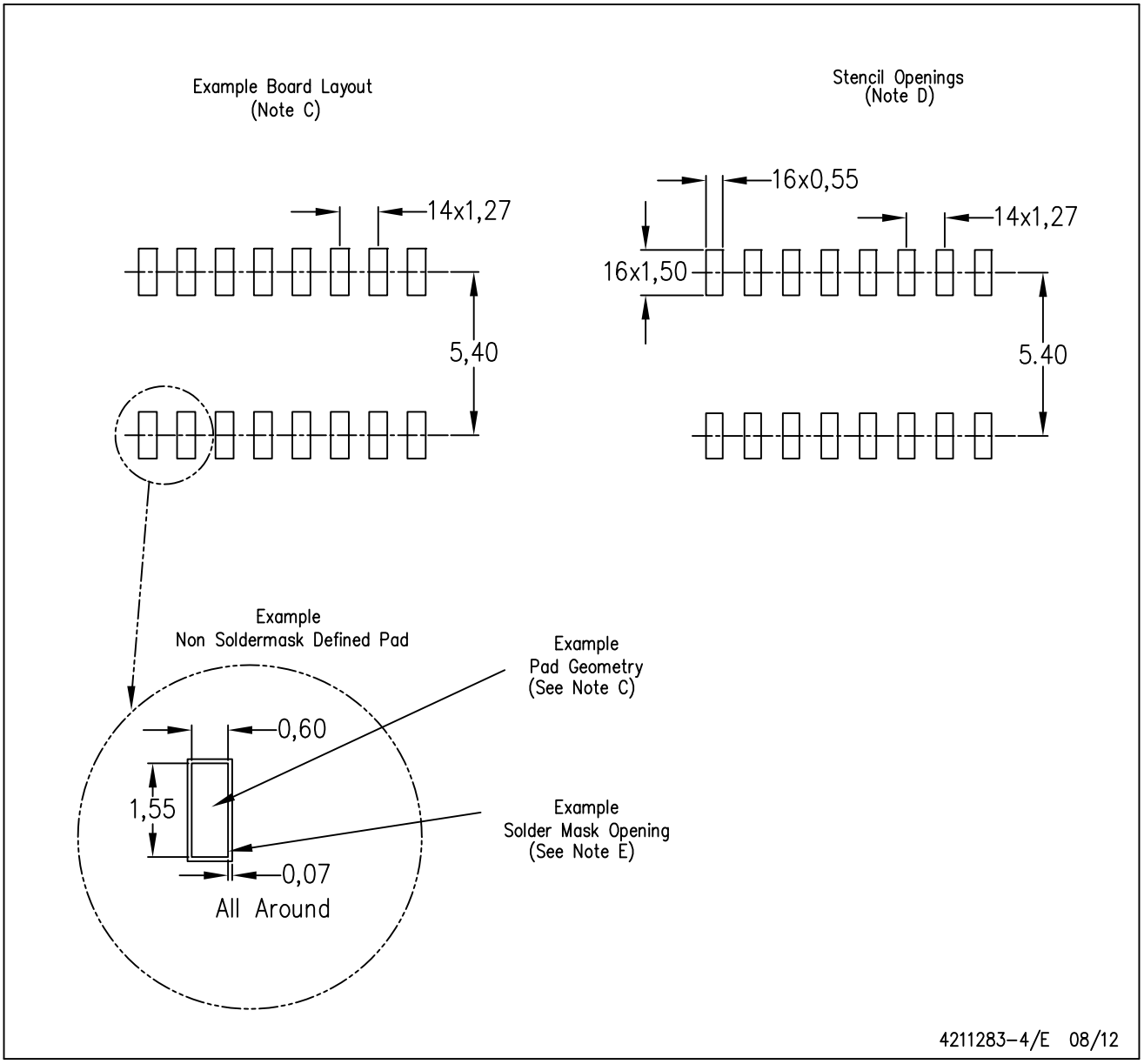
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9164001Q2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9164001QFA	W	CFP	16	1	506.98	26.16	6220	NA
AM26C32CD	D	SOIC	16	40	507	8	3940	4.32
AM26C32CDE4	D	SOIC	16	40	507	8	3940	4.32
AM26C32CN	N	PDIP	16	25	506	13.97	11230	4.32
AM26C32CN	N	PDIP	16	25	506	13.97	11230	4.32
AM26C32CNE4	N	PDIP	16	25	506	13.97	11230	4.32
AM26C32CNE4	N	PDIP	16	25	506	13.97	11230	4.32
AM26C32ID	D	SOIC	16	40	507	8	3940	4.32
AM26C32IDE4	D	SOIC	16	40	507	8	3940	4.32
AM26C32IDG4	D	SOIC	16	40	507	8	3940	4.32
AM26C32IN	N	PDIP	16	25	506	13.97	11230	4.32
AM26C32IPW	PW	TSSOP	16	90	530	10.2	3600	3.5
AM26C32IPWG4	PW	TSSOP	16	90	530	10.2	3600	3.5
AM26C32MFKB	FK	LCCC	20	1	506.98	12.06	2030	NA
AM26C32MWB	W	CFP	16	1	506.98	26.16	6220	NA
AM26C32QD	D	SOIC	16	40	505.46	6.76	3810	4
AM26C32QDG4	D	SOIC	16	40	505.46	6.76	3810	4

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



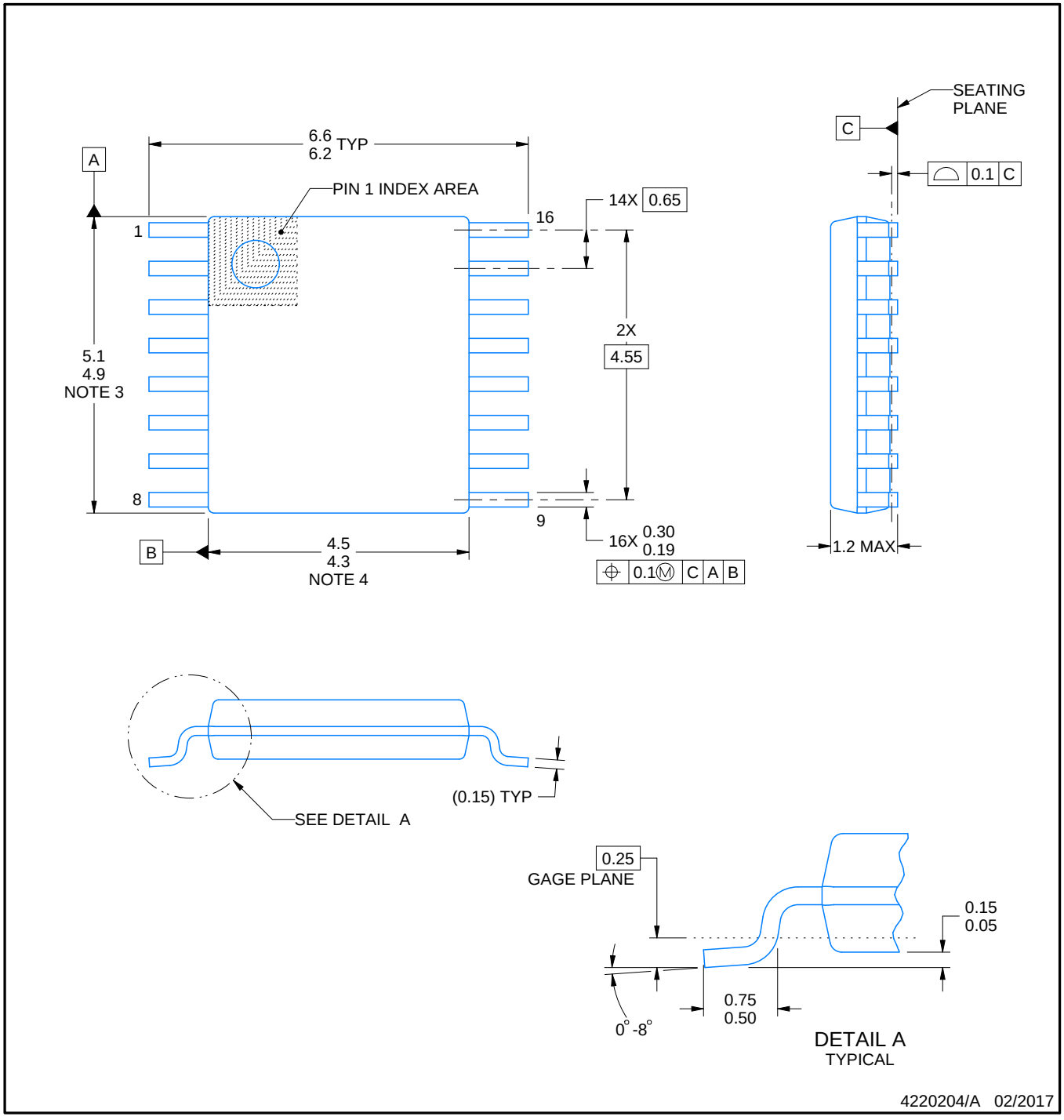
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PACKAGE OUTLINE

PW0016A

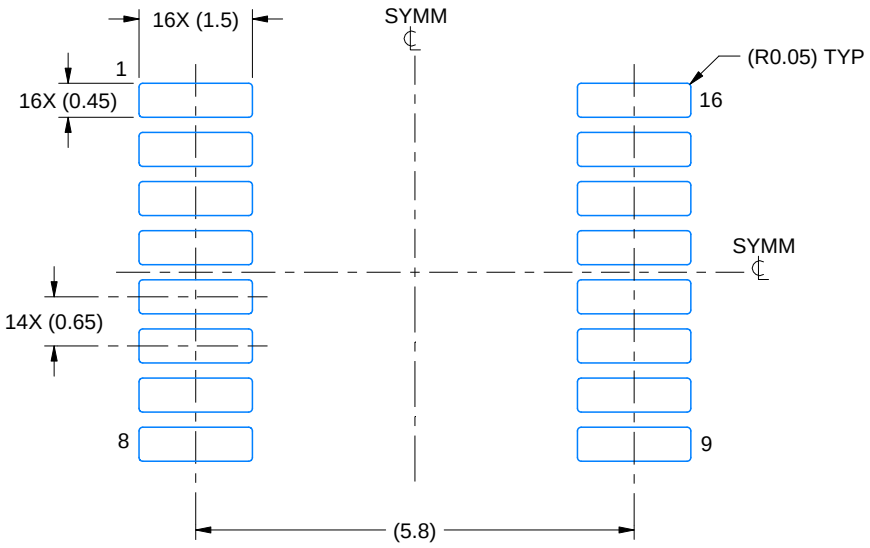
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

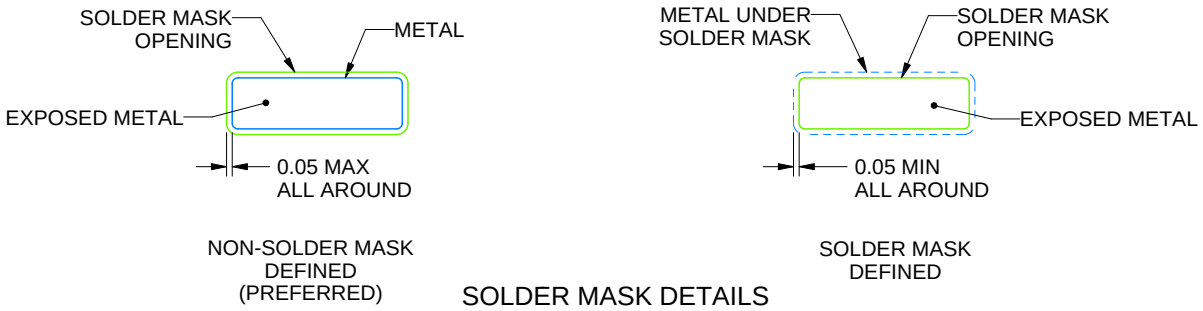


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

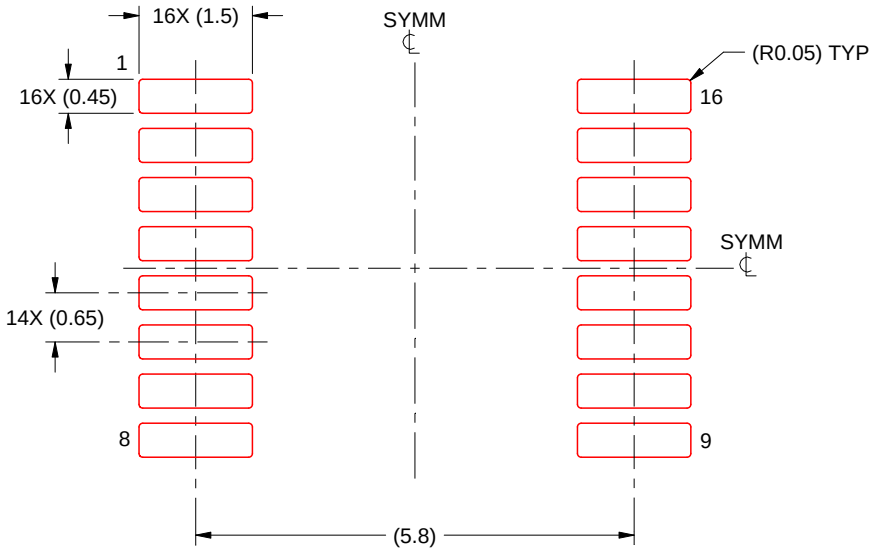


SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

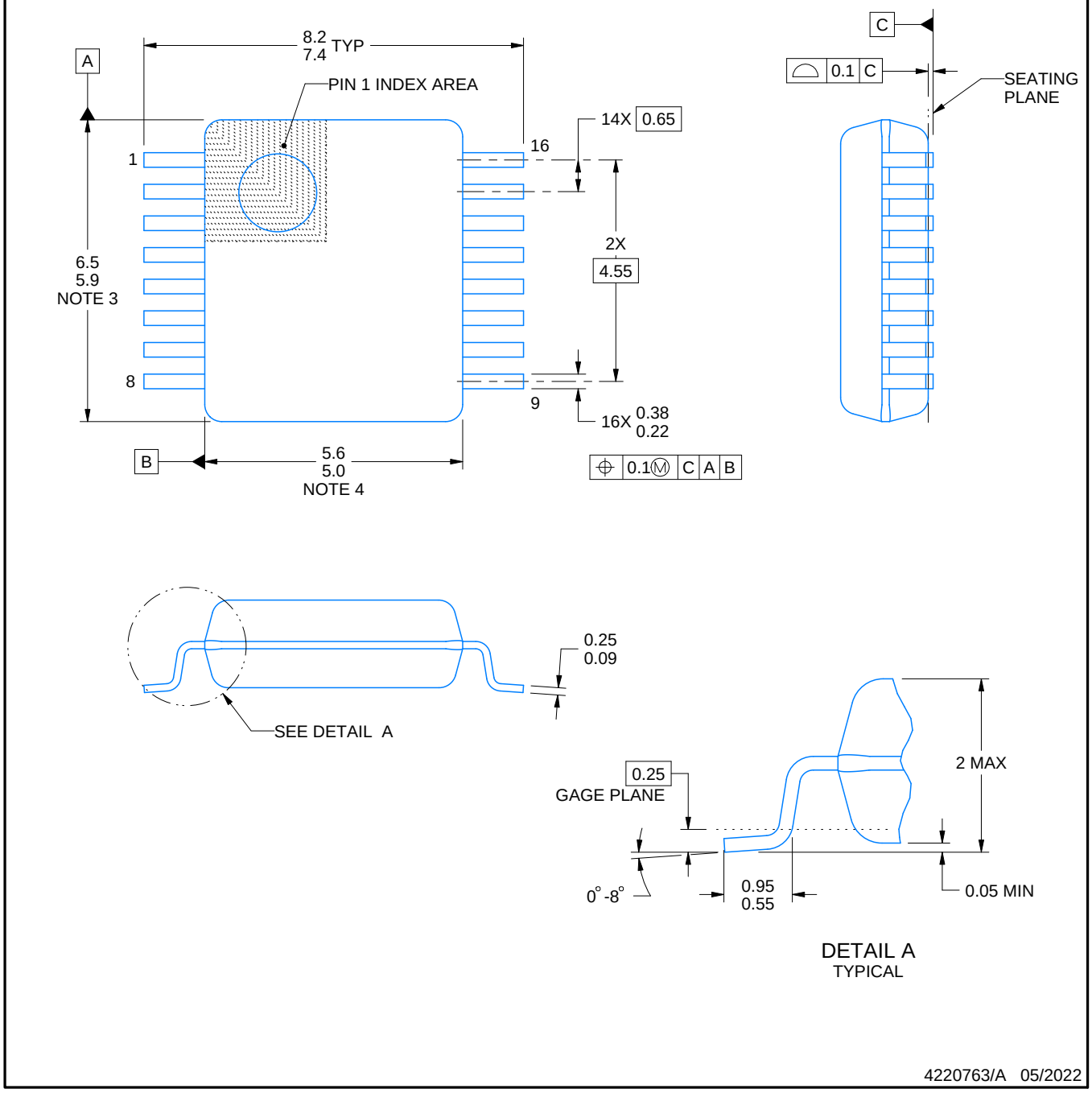
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DB0016A

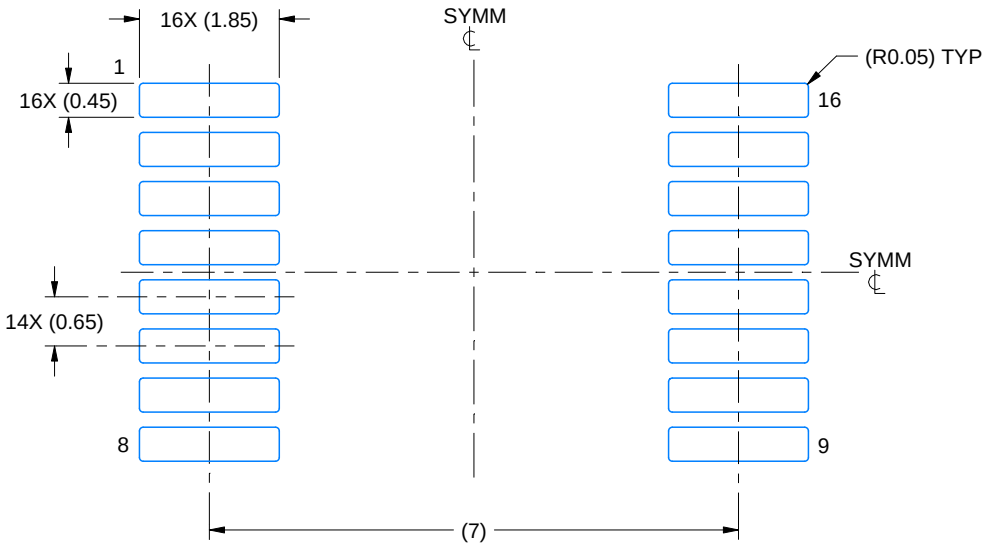
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

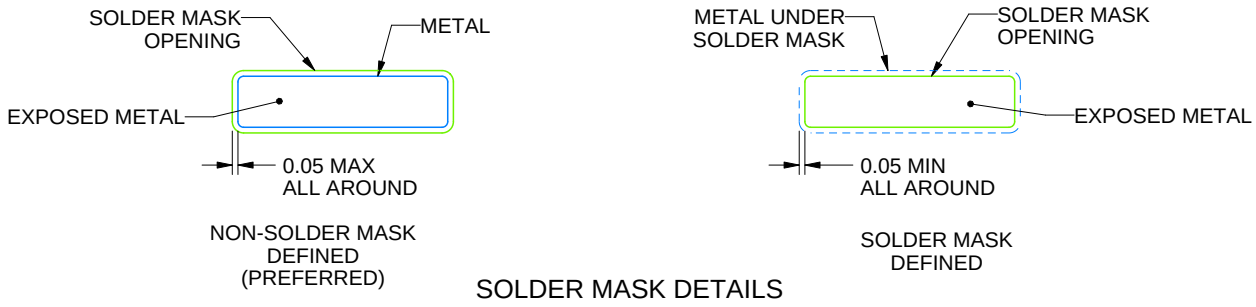


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

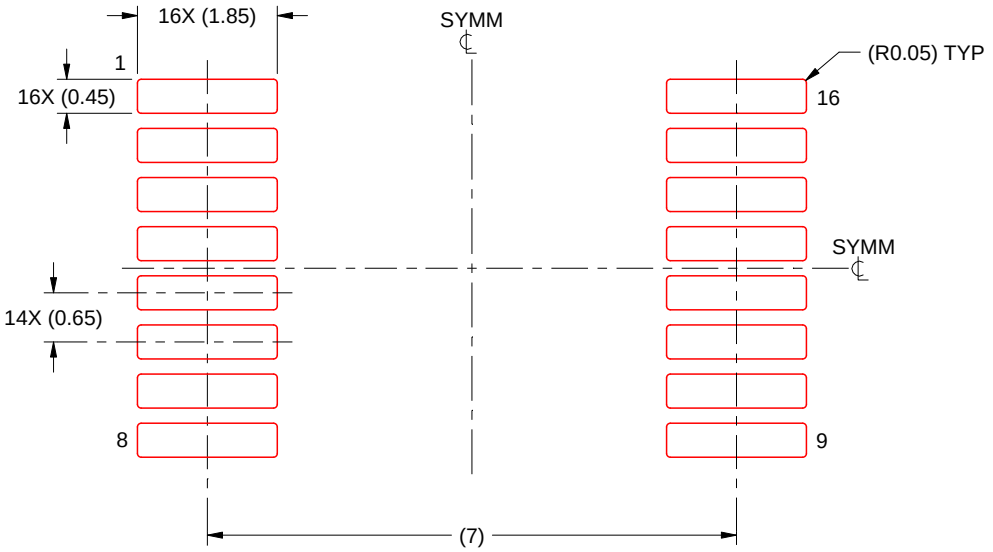


SOLDER MASK DETAILS

4220763/A 05/2022

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

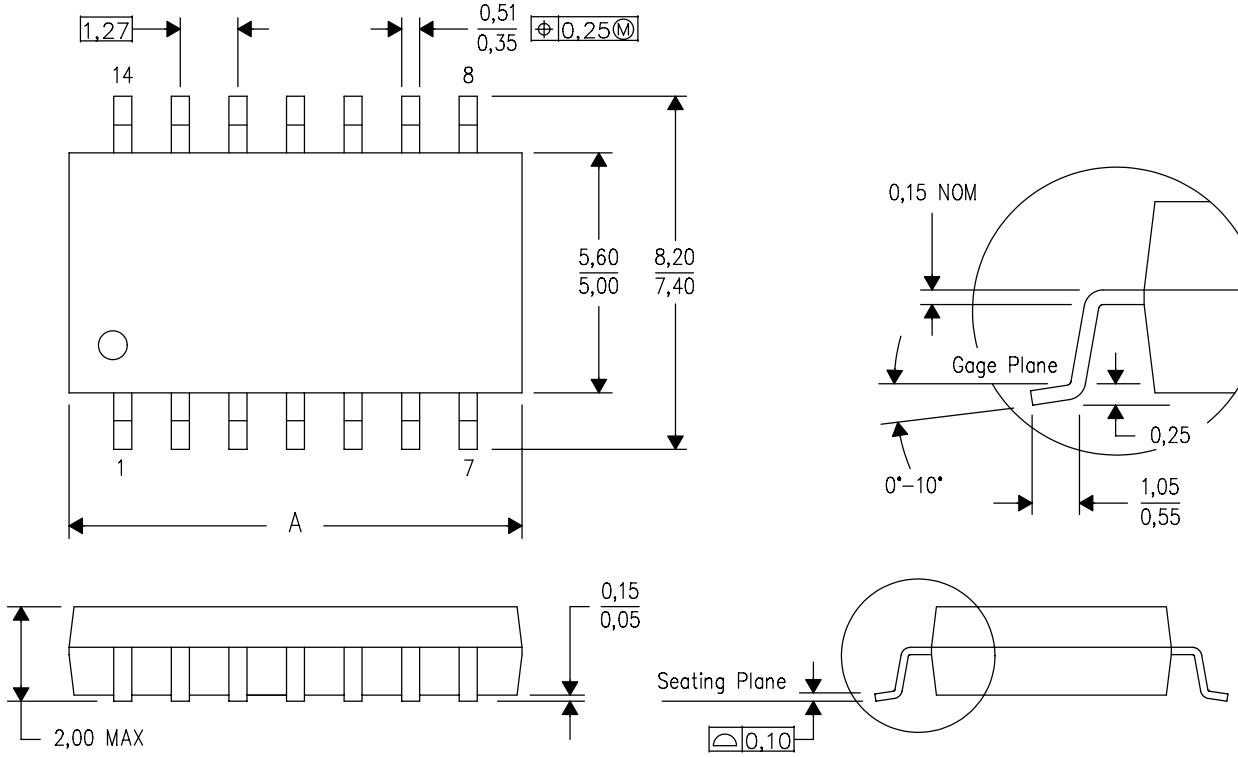
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

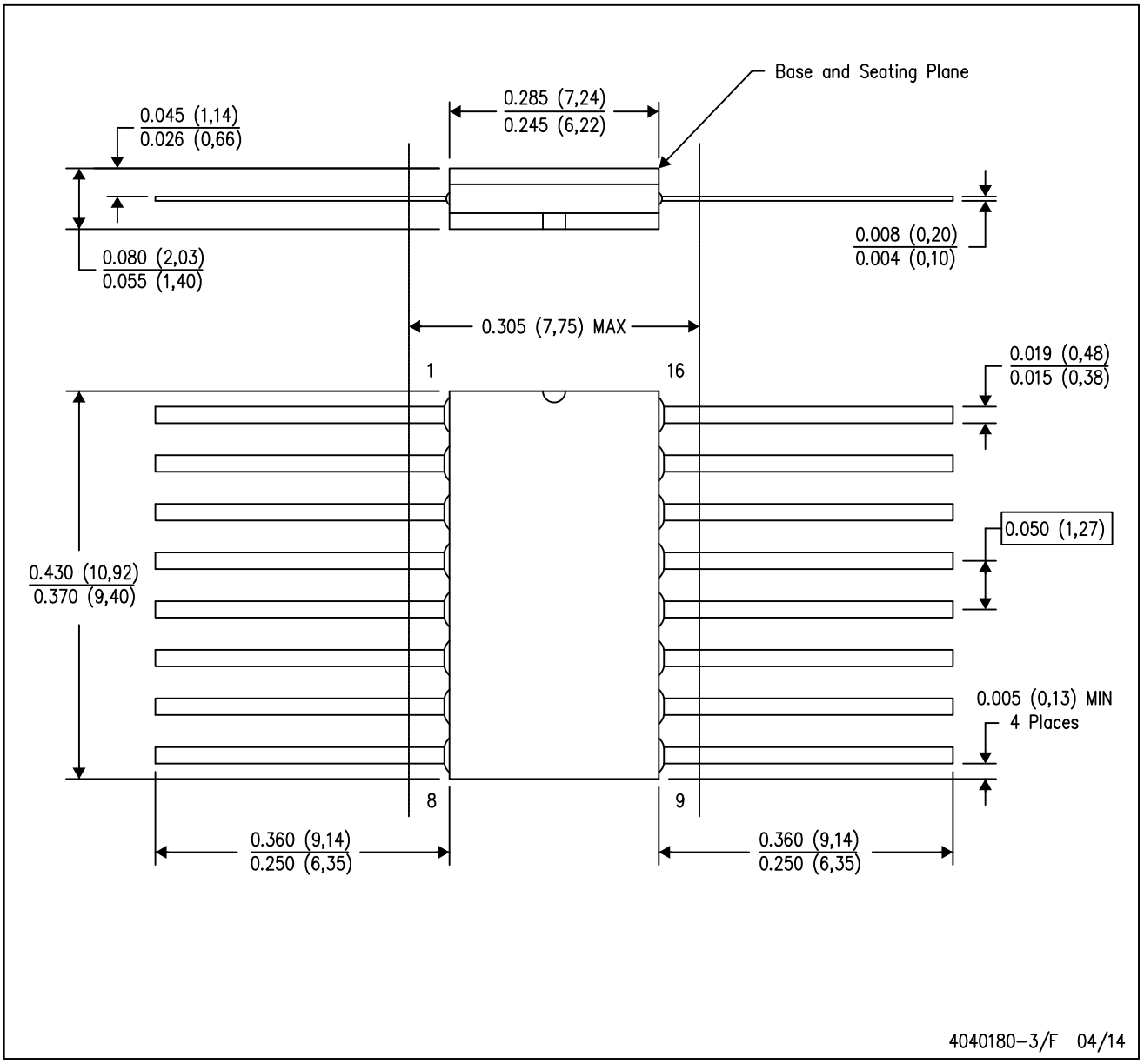


DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R–GDFP–F16) CERAMIC DUAL FLATPACK

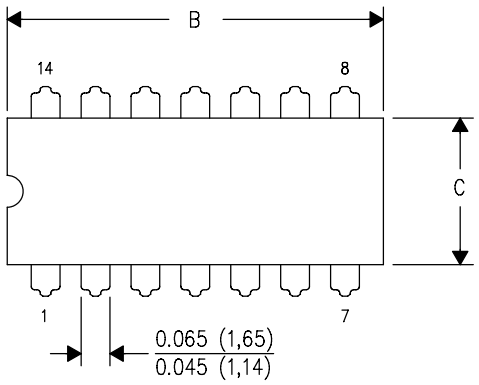


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

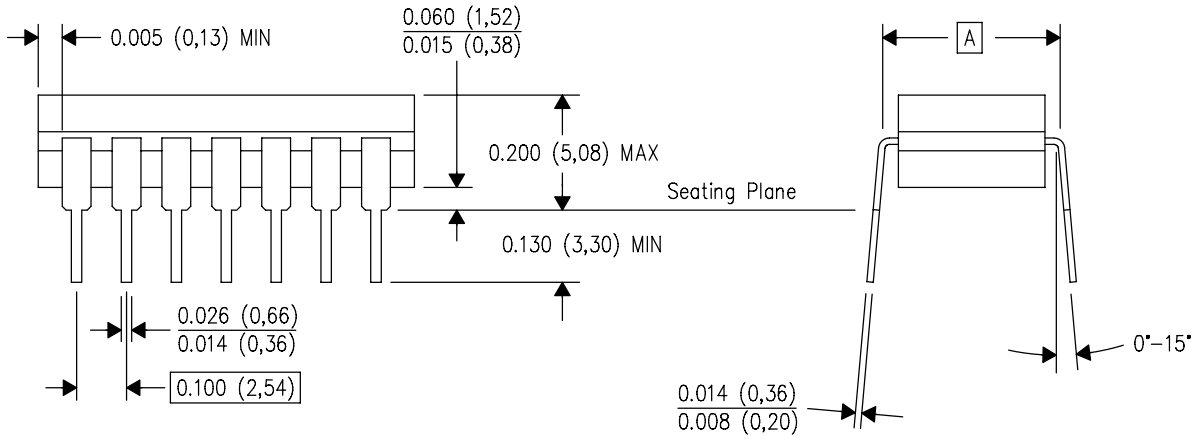
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



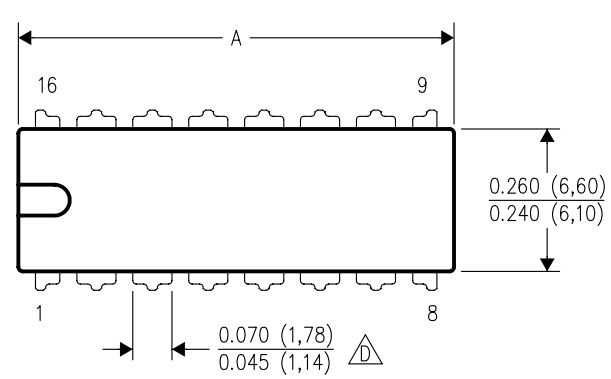
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

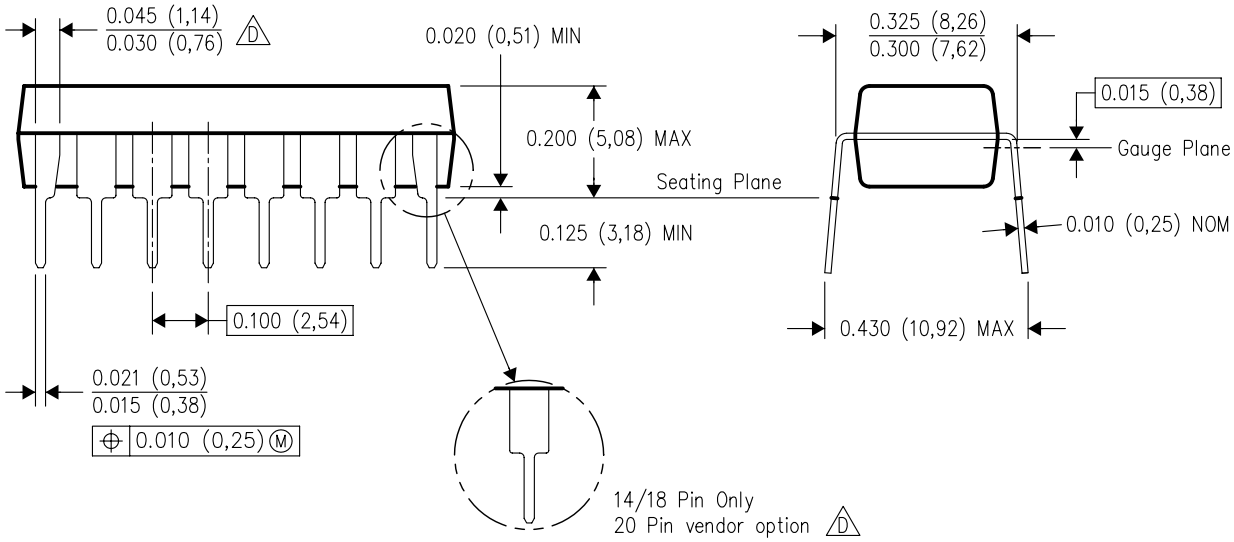
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

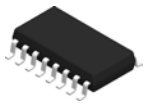


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

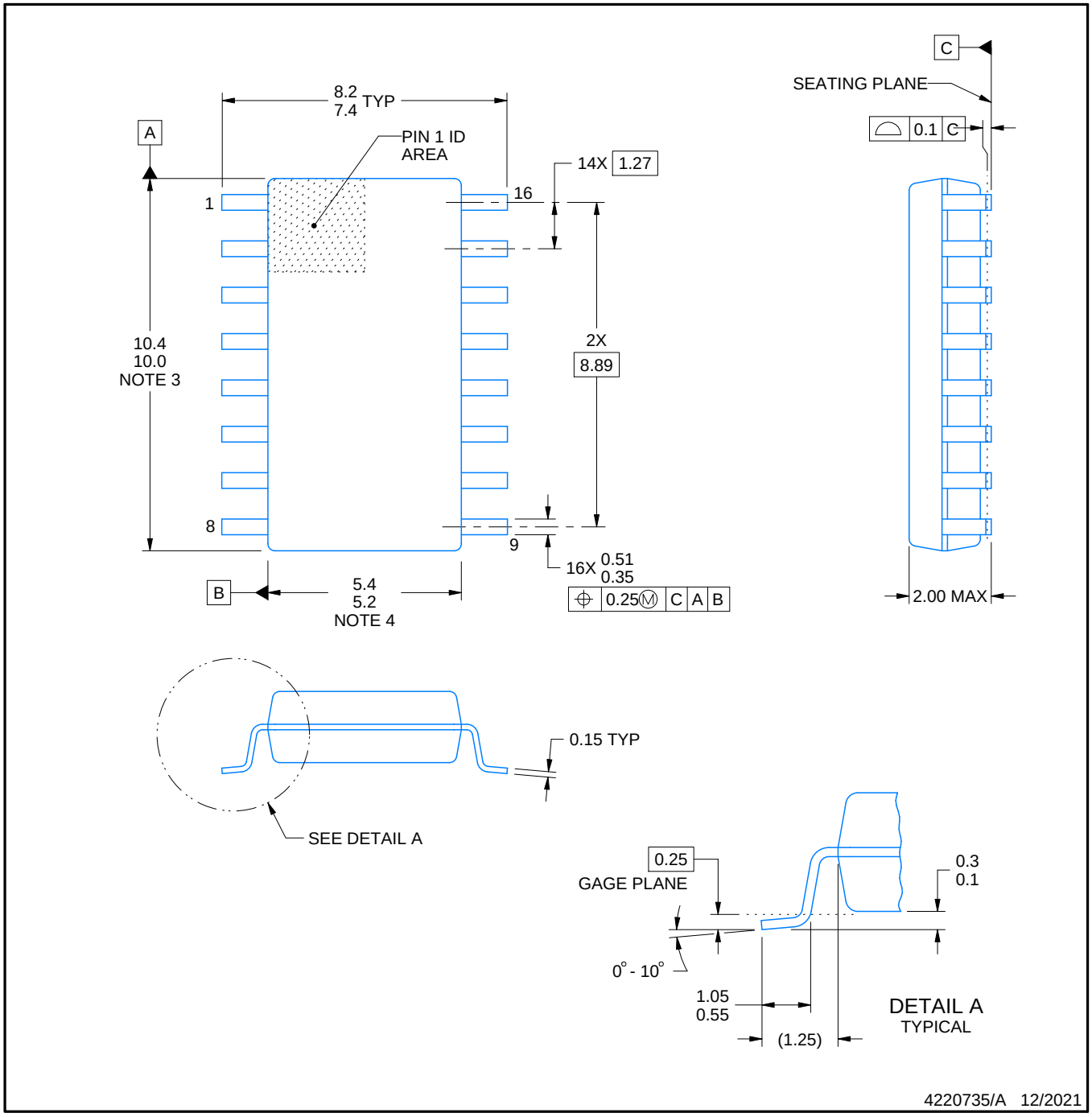


PACKAGE OUTLINE

NS0016A

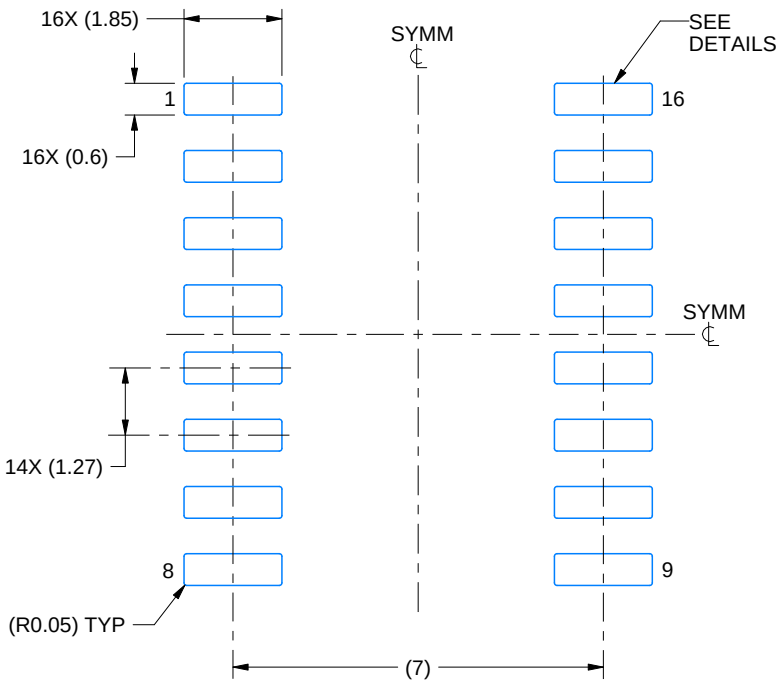
SOP - 2.00 mm max height

SOP

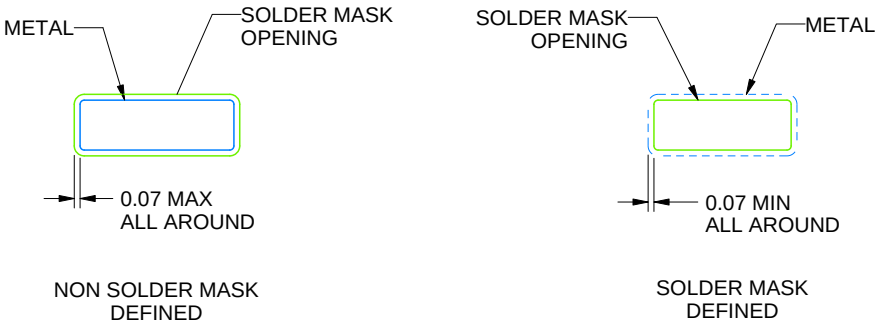


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

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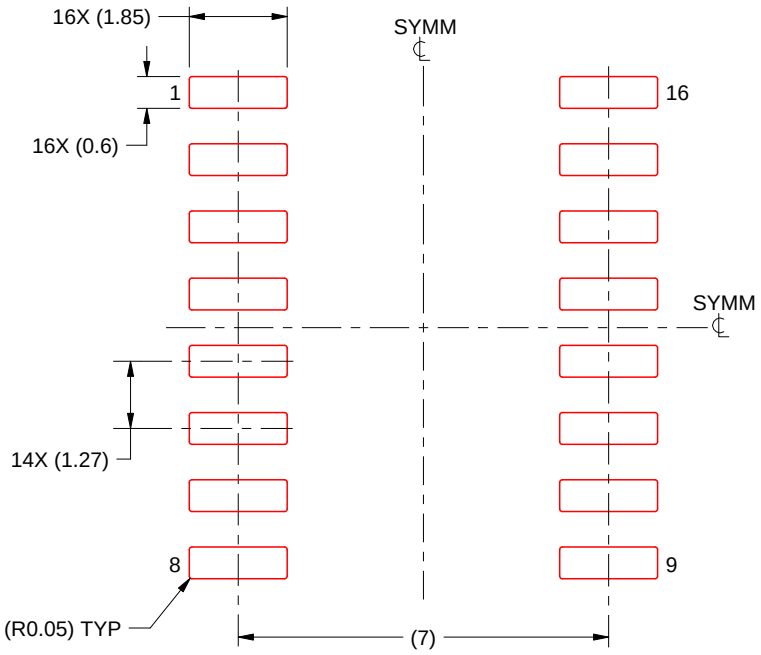
NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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